## Sensor Manufacturing

### Photoresists

Our broadband, I-line and G-line spin on photoresists are formulated to provide high resolution, vertical profiles, outstanding depth of focus, plasma and wet etch resistance, good plating performance and superior adhesion. Applications include:

- CMOS
- High Energy Implants
- MEMS
- GaAs
- Thin Film Head
- Bump
- Other Specialty Applications

### Substrates

Our synthetic quartz wafers and substrates, bonded SOI and other specialty wafers have exceptional properties required for the following applications:

- MEMS
- RF Devices
- TFT-LCD

### Resins

Our solvent and water based resins are available as binders for conductive inks. Printing types include:

- Gravure
- Screen Printing
- Inkjet

## Sensor Packaging & Assembly

### Silicones

Our silicone based materials were developed for MEMS mounted sensors, smaller package devices and high performance devices. We offer single component heat cure silicone gel, polyimide silicone, and fluorosilicone materials for the following applications:

- Die Bonding
- Electrode Encapsulation and Chip Coating
- Frame and EMC Stress Relief

### Photoimageable Dielectrics

Our photoimageable dielectrics are key performance materials for advanced packaging applications, wafer-level packaging, and 3D integration. Applications include:

- Stress Buffer
- TSV Filling
- Permanent Wafer Bonding
- Redistribution Wiring (RDL)

### Resins

Our solvent and water based resins for coatings, adhesives, sealants, and encapsulates offer chemical resistance, toughness, flexibility and flame resistance. We offer Vinyl Chloride Copolymers, Acrylic, Polyurethane and Silicone Hybrids for the following applications:

- Flexible Textile Coatings
- Adhesives
- Protective Coatings and Encapsulation
### Photoresists

**G/I/H Line Resists**
- SIPR 3251M
- SIPR 9332M
- SIPR 7120 Series

### Silicones

**Die Bonding**
- KER-6020-F/F1/F2, KER-3500-P2

**Electrode Encapsulation & Chip Coating**
- KER-6021, KER-2201, FE-73, FE-78-A/B

**Frame and EMC Stress Relief**
- SMP-2840, SMP-5005PGMEA, SMP-5008PGMEA

### Photoimageable Dielectrics

**Siloxane Polymer**
- SINR 3170M
- SINR 3570M

### Substrates

**Synthetic Quartz Wafers and Substrates**
- VIOSIL-SQ, VIOSIL-SX

**Bonded Silicon on Insulator (SOI) Wafers**
- Silicon on Sapphire (SOS), Silicon on Quartz (SOQ)

**Resins**

**Solvent based VC/VAc Copolymers**
- SOLBIN

**Water based VC/VAc, VC/Acrylic Acid Ester, VC/Polyurethane Emulsions**
- VINYBLAN

**Silicone/Acrylic Hybrid**
- CHALINE